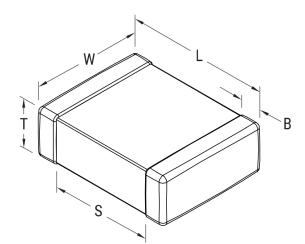


## C0603X222K1GECTU

Aliases (C0603X222K1GEC7867)

ESD SMD Comm COG, Ceramic, 2200 pF, 10%, 100 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0603



Click here for the 3D model.

Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.58mm MIN
В	0.45mm +/-0.15mm

## Packaging Specifications Packaging T&R Packaging Quantity 400

T&R, 180mm, Paper Tape 4000

General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Component Weight	4.6 mg
Shelf Life	78 Weeks
MSL	1

Specifications		
Capacitance	2200 pF	
Measurement Condition	1 kHz 1.0Vrms	
Capacitance Tolerance	10%	
Voltage DC	100 VDC	
ESD Level per AEC-Q200	12,000 V ESD Level	
Dielectric Withstanding Voltage	250 VDC	
Temperature Range	-55/+125°C	
Temperature Coefficient	COG	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour	
Insulation Resistance	100 GOhms	

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